

SMT850-27

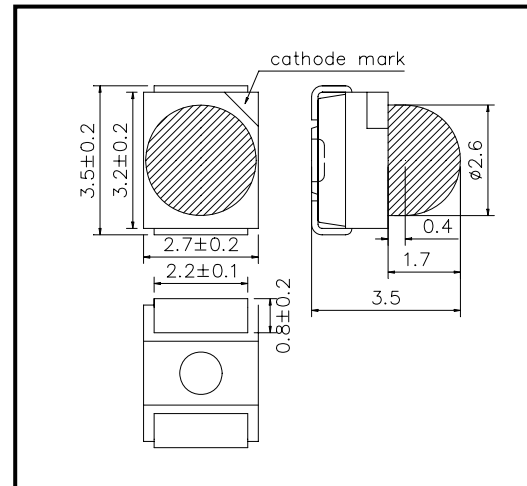
High Performance Infrared TOP LED with Lens

SMT850-27 consists of an AlGaAs LED mounted on the lead frame as TOP LED package with plastic ball lens and is 44mW typical of output power and 40mW/sr of radiant Intensity. It emits a spectral band of radiation at 850nm.

◆ Outer dimension (Unit:mm)

◆ Specifications

1) Product Name	TOP IR LED
2) Type No.	SMT850-27
3) Chip	
(1) Chip Material	AlGaAs
(2) Chip Dimension	400um*400nm
(3) Peak Wavelength	850nm typ.
4) Package	
(1) Lead Frame Die	Silver Plated
(2) Package Resin	PPA Resin
(3) Lens	Epoxy Resin
(4) Diameter	Φ2.6mm



◆ Absolute Maximum Rating

Item	Symbol	Maximum Rated Value	Unit	Ambient Temperature
Power Dissipation	P _D	160	mW	T _a =25°C
Forward Current	I _F	100	mA	T _a =25°C
Pulse Forward Current	I _{FP}	500	mA	T _a =25°C
Reverse Voltage	V _R	5	V	T _a =25°C
Operating Temperature	T _{OPR}	-20 ~ +80	°C	
Storage Temperature	T _{STG}	-30 ~ +80	°C	
Soldering Temperature	T _{SOL}	255	°C	

‡Pulse Forward Current condition: Duty=1% and Pulse Width=10us.

‡Soldering condition: Soldering condition must be completed within 10 seconds at 255°C

◆ Electro-Optical Characteristics [T_a=25°C]

Item	Symbol	Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	V _F	I _F =50mA DC		1.45	1.60	V
		I _F =100mA, t _p =20ms		1.50	1.8	
Reverse Current	I _R	V _R =5V			10	uA
Total Radiated Power	P _O	I _F =50mA DC	16.0	22.0		mW
		I _F =100mA, t _p =20ms		44.0		
Radiant Intensity	I _E	I _F =50mA DC		20		mW/sr
		I _F =100mA, t _p =20ms		40		
Peak Wavelength	λ _P	I _F =50mA DC	835	850	865	nm
Half Width	Δλ	I _F =50mA DC		40		nm
Viewing Half Angle	θ _{1/2}	I _F =50mA DC		±28		deg.
Rise Time	t _r	I _F =50mA DC		15		ns
Fall Time	t _f	I _F =50mA DC		10		ns

‡Total Radiated Power is measured by Photodyne #500

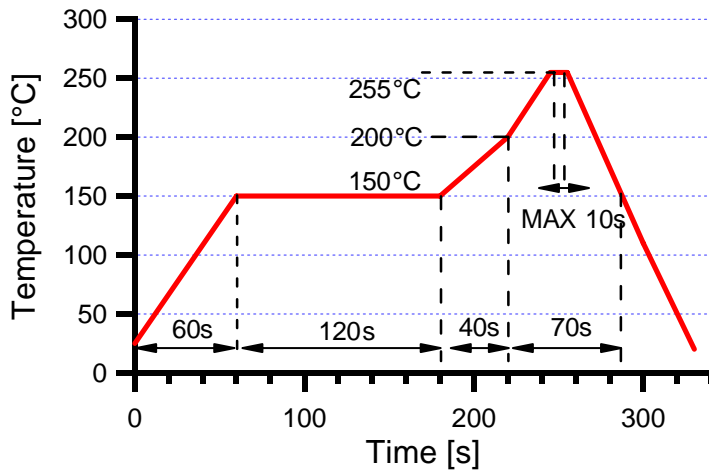
‡Radiant Intensity is measured by Tektronix J-6512.

USHIO EUROPE B.V. (www.ushio.eu)

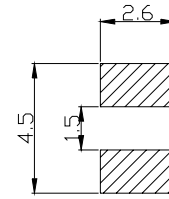
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◆ SMD Application
IR-Reflow Soldering Profile for lead free soldering

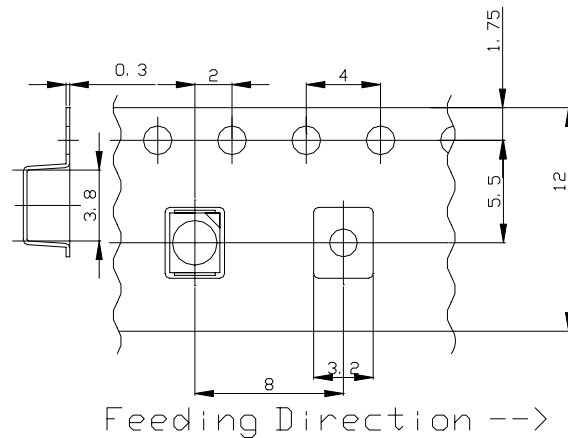
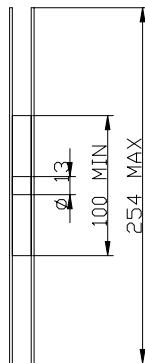
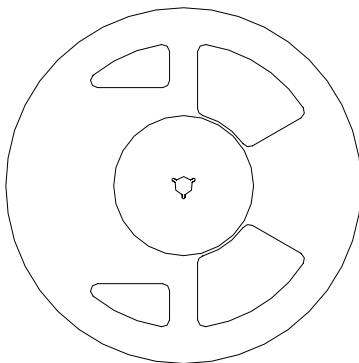


Recommended Land Layout (Unit: mm)



Don't put stress on SMD and a circuit board after soldering.

◆ SMD Packing
Tape and Reel Dimensions (Unit: mm)



◆ Wrapping

Moisture barrier bag aluminum laminated film with a desiccant to keep out the moisture absorption during the transportation and storage.